ABSTRACT

This invention relates to a polishing pad and a method for manufacturing the same. The polishing pad may include a top pad layer and a window block. The top pad layer may include a groove pattern formed on an upper surface of the top pad layer. A first hole may be formed through the top pad layer. The window block may be inserted into the first hole. The top pad layer and the window block may have a structure coincided with following Formula 1.

Formula 1

$$1.1 \leq \frac{\mathrm{Gap} + \mathrm{Thk_{RTPC}}}{\mathrm{Thk_{grv}}} \leq 3.0$$

In Formula 1, the gap may indicate a height difference between an upper surface of the top pad layer and an upper surface of the window block, the Thk_{RTPC} may indicate a thickness of the window block, and the Thk_{grv} may indicate a depth of the groove pattern.

FIG. 2